



**General Description**

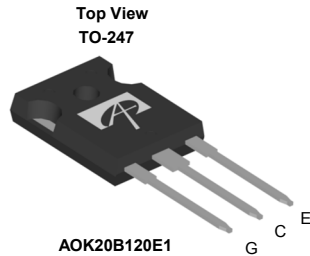
- Latest AlphaIGBT ( $\alpha$  IGBT) technology
- Best in Class  $V_{CE(SAT)}$  enables high efficiencies
- Low turn-off switching loss due to fast turn-off time
- Very smooth turn-off current waveforms reduce EMI
- Better thermal management
- High surge current capability
- Minimal gate spike due to high input capacitance

**Applications**

- Induction Cooking
- Rice Cookers
- Microwave Ovens
- Other soft switching applications

**Product Summary**

$V_{CE}$	1200V
$I_C$ ( $T_C=100^\circ\text{C}$ )	20A
$V_{CE(sat)}$ ( $T_C=25^\circ\text{C}$ )	1.68V



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOK20B120E1	TO247	Tube	240

**Absolute Maximum Ratings  $T_A=25^\circ\text{C}$  unless otherwise noted**

Parameter	Symbol	AOK20B120E1	Units
Collector-Emitter Voltage	$V_{CE}$	1200	V
Gate-Emitter Voltage	$V_{GE}$	$\pm 30$	V
Continuous Collector Current	$I_C$	$T_C=25^\circ\text{C}$	40
		$T_C=100^\circ\text{C}$	20
Pulsed Collector Current, Limited by $T_{Jmax}$	$I_{Cpulse}$	80	A
Non repetitive peak collector current <sup>A</sup>	$I_{CSM}$	200	A
Turn off SOA, $V_{CE} \leq 600\text{V}$ , Limited by $T_{Jmax}$	$I_{LM}$	80	A
Continuous Diode Forward Current	$I_F$	$T_C=25^\circ\text{C}$	40
		$T_C=100^\circ\text{C}$	20
Diode Pulsed Current, Limited by $T_{Jmax}$	$I_{Fpulse}$	80	A
Power Dissipation	$P_D$	$T_C=25^\circ\text{C}$	333
		$T_C=100^\circ\text{C}$	167
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 175	$^\circ\text{C}$
Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	$T_L$	300	$^\circ\text{C}$

**Thermal Characteristics**

Parameter	Symbol	AOK20B120E1	Units
Maximum Junction-to-Ambient	$R_{\theta JA}$	40	$^\circ\text{C/W}$
Maximum IGBT Junction-to-Case	$R_{\theta JC}$	0.45	$^\circ\text{C/W}$
Maximum Diode Junction-to-Case	$R_{\theta JC}$	1.6	$^\circ\text{C/W}$

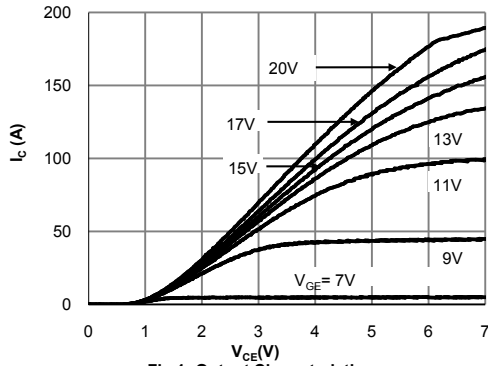
Note A: Capacitor charging saturation current limited by  $T_{Jmax} < 175^\circ\text{C}$  and  $t_p < 3\mu\text{s}$

**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

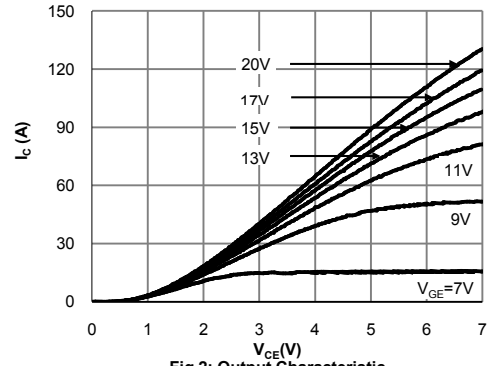
Symbol	Parameter	Conditions	Min	Typ	Max	Units	
<b>STATIC PARAMETERS</b>							
$BV_{CES}$	Collector-Emitter Breakdown Voltage	$I_C=1mA, V_{GE}=0V, T_J=25^\circ C$	1200	-	-	V	
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15V, I_C=20A$	$T_J=25^\circ C$	-	1.68	2.1	V
			$T_J=125^\circ C$	-	2	-	
			$T_J=175^\circ C$	-	2.2	-	
$V_F$	Diode Forward Voltage	$V_{GE}=0V, I_C=20A$	$T_J=25^\circ C$	-	1.6	2	V
			$T_J=125^\circ C$	-	1.68	-	
			$T_J=175^\circ C$	-	1.7	-	
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$V_{CE}=5V, I_C=1mA$	4.5	5.15	5.8	V	
$I_{CES}$	Zero Gate Voltage Collector Current	$V_{CE}=1200V, V_{GE}=0V$	$T_J=25^\circ C$	-	-	10	μA
			$T_J=125^\circ C$	-	-	500	
			$T_J=175^\circ C$	-	-	5000	
$I_{GES}$	Gate-Emitter leakage current	$V_{CE}=0V, V_{GE}=\pm 30V$	-	-	±100	nA	
$g_{FS}$	Forward Transconductance	$V_{CE}=20V, I_C=20A$	-	23	-	S	
<b>DYNAMIC PARAMETERS</b>							
$C_{ies}$	Input Capacitance	$V_{GE}=0V, V_{CE}=25V, f=1MHz$	-	1620	-	pF	
$C_{oes}$	Output Capacitance		-	90	-	pF	
$C_{res}$	Reverse Transfer Capacitance		-	28	-	pF	
$Q_g$	Total Gate Charge	$V_{GE}=15V, V_{CE}=960V, I_C=20A$	-	60.5	-	nC	
$Q_{ge}$	Gate to Emitter Charge		-	14.5	-	nC	
$Q_{gc}$	Gate to Collector Charge		-	28	-	nC	
$R_g$	Gate resistance	$V_{GE}=0V, V_{CE}=0V, f=1MHz$	-	2.1	-	Ω	
<b>SWITCHING PARAMETERS, (Load Inductive, T<sub>J</sub>=25°C)</b>							
$t_{D(off)}$	Turn-Off Delay Time	$T_J=25^\circ C$	-	134	-	ns	
$t_f$	Turn-Off Fall Time	$V_{GE}=15V, V_{CE}=600V, I_C=20A,$ $R_G=15\Omega,$	-	98	-	ns	
$E_{off}$	Turn-Off Energy	Parasitic Inductance=150nH	-	0.83	-	mJ	
<b>SWITCHING PARAMETERS, (Load Inductive, T<sub>J</sub>=175°C)</b>							
$t_{D(off)}$	Turn-Off Delay Time	$T_J=175^\circ C$	-	155	-	ns	
$t_f$	Turn-Off Fall Time	$V_{GE}=15V, V_{CE}=600V, I_C=20A,$ $R_G=15\Omega,$	-	184	-	ns	
$E_{off}$	Turn-Off Energy	Parasitic Inductance=150nH	-	1.37	-	mJ	

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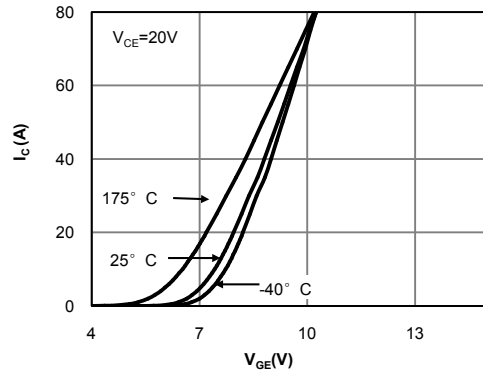
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**



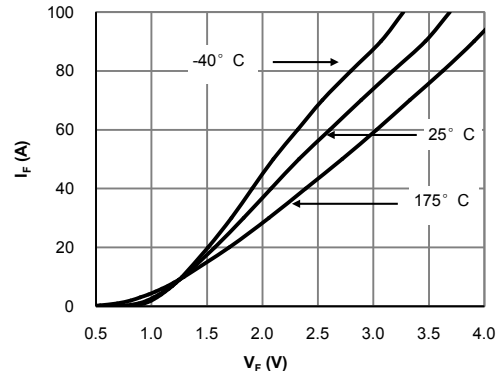
**Fig 1: Output Characteristic**  
( $T_j=25^\circ\text{C}$ )



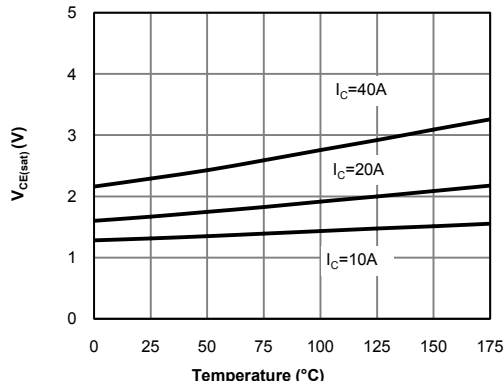
**Fig 2: Output Characteristic**  
( $T_j=175^\circ\text{C}$ )



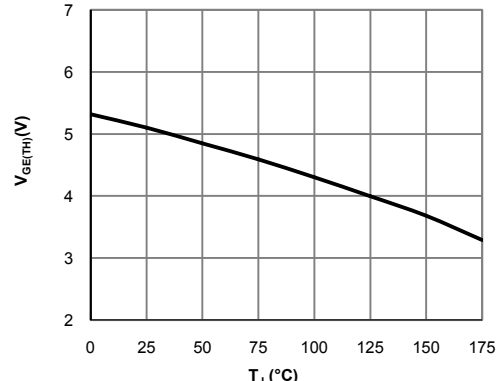
**Fig 3: Transfer Characteristic**



**Fig 4: Diode Characteristic**

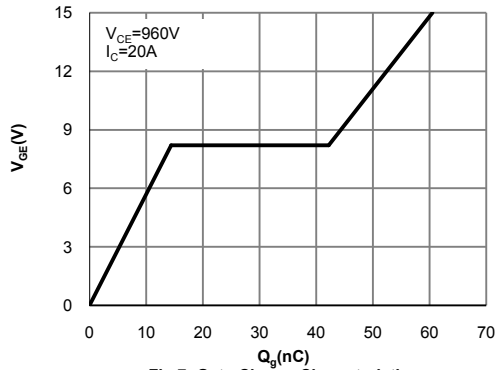


**Fig 5: Collector-Emitter Saturation Voltage vs. Junction Temperature**

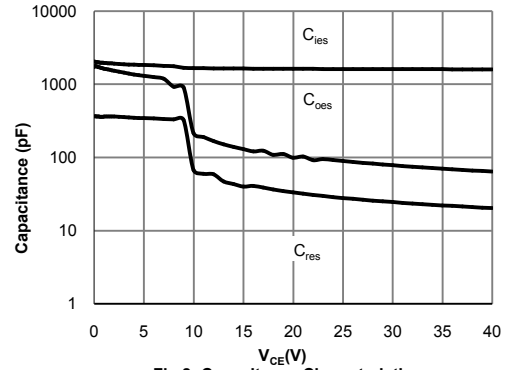


**Figure 6:  $V_{GE(TH)}$  vs.  $T_j$**

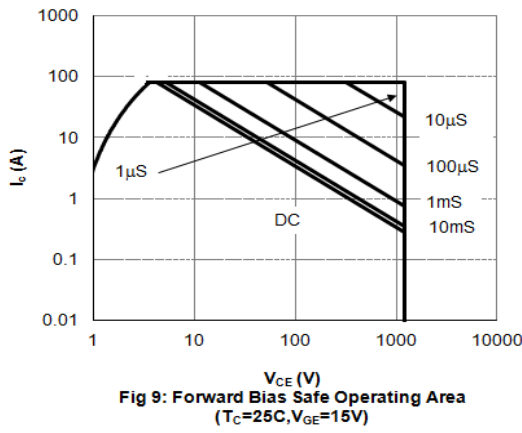
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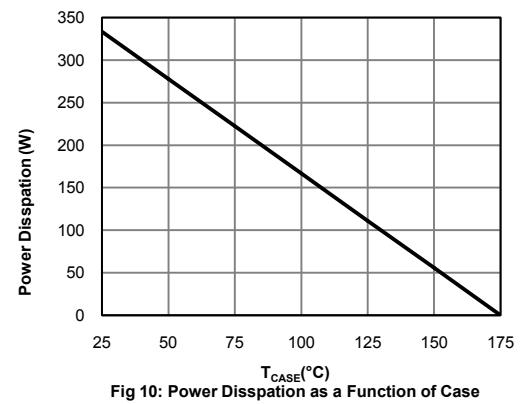
**Fig 7: Gate-Charge Characteristics**



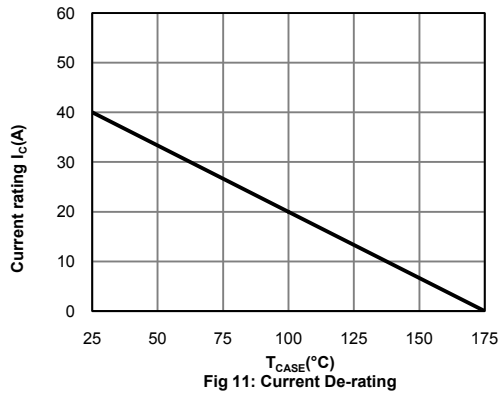
**Fig 8: Capacitance Characteristic**



**Fig 9: Forward Bias Safe Operating Area**  
( $T_C=25^\circ\text{C}$ ,  $V_{GE}=15\text{V}$ )

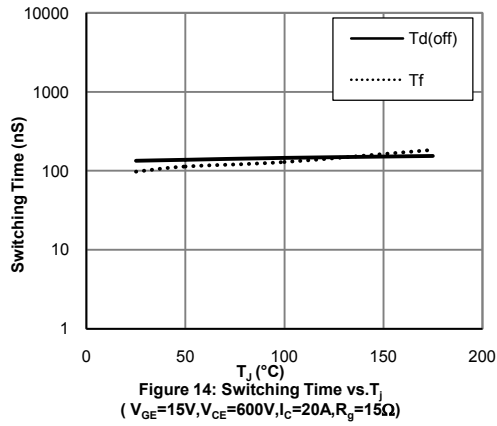
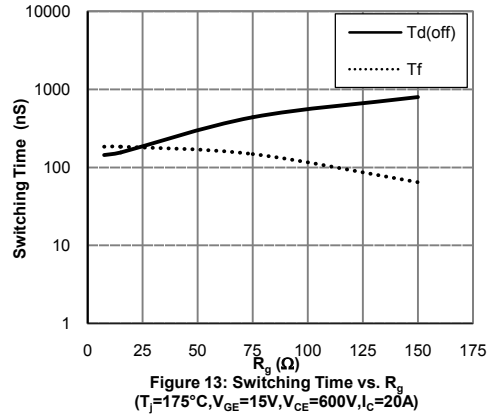
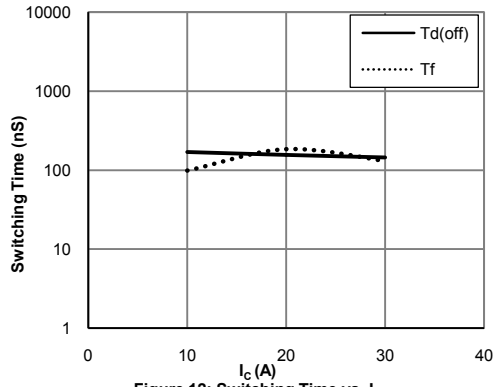


**Fig 10: Power Dissipation as a Function of Case**

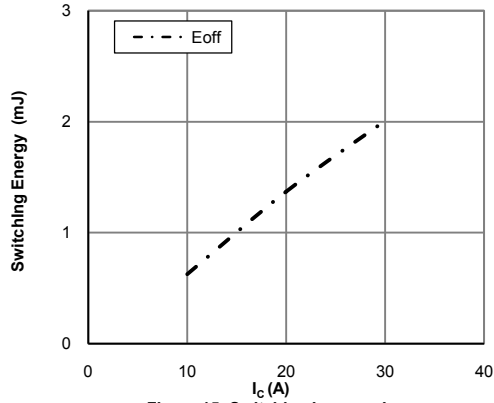


**Fig 11: Current De-rating**

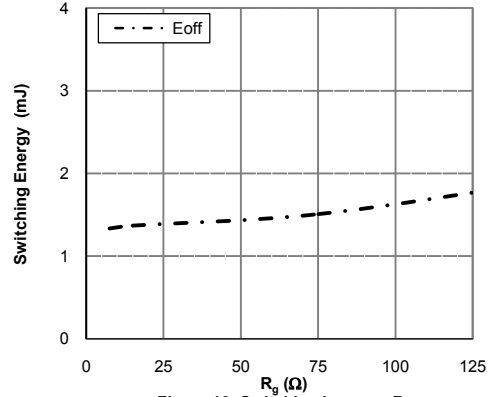
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**



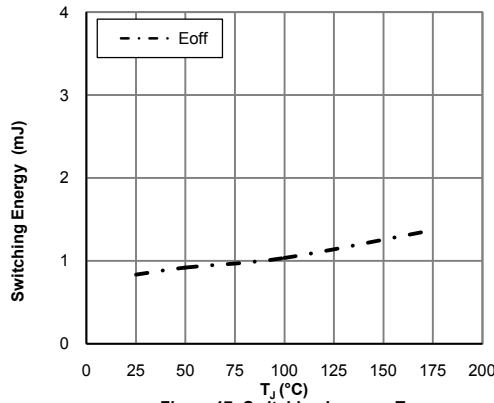
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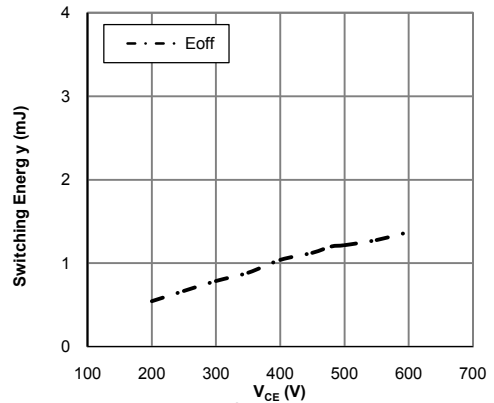
**Figure 15: Switching Loss vs.  $I_C$**   
( $T_J=175^\circ\text{C}, V_{GE}=15\text{V}, V_{CE}=600\text{V}, R_\theta=15\Omega$ )



**Figure 16: Switching Loss vs.  $R_g$**   
( $T_J=175^\circ\text{C}, V_{GE}=15\text{V}, V_{CE}=600\text{V}, I_C=20\text{A}$ )

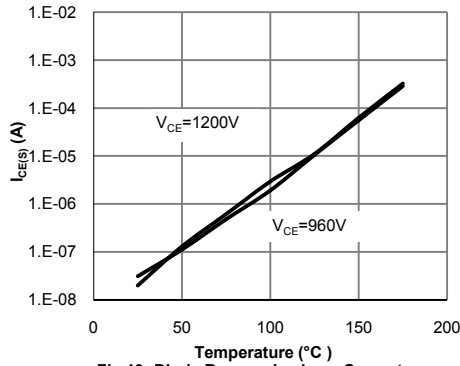


**Figure 17: Switching Loss vs.  $T_J$**   
( $V_{GE}=15\text{V}, V_{CE}=600\text{V}, I_C=20\text{A}, R_\theta=15\Omega$ )

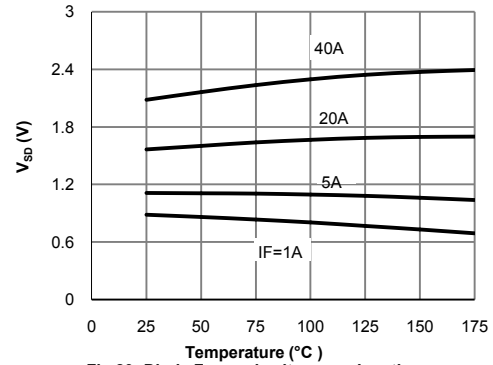


**Figure 18: Switching Loss vs.  $V_{CE}$**   
( $T_J=175^\circ\text{C}, V_{GE}=15\text{V}, I_C=20\text{A}, R_\theta=15\Omega$ )

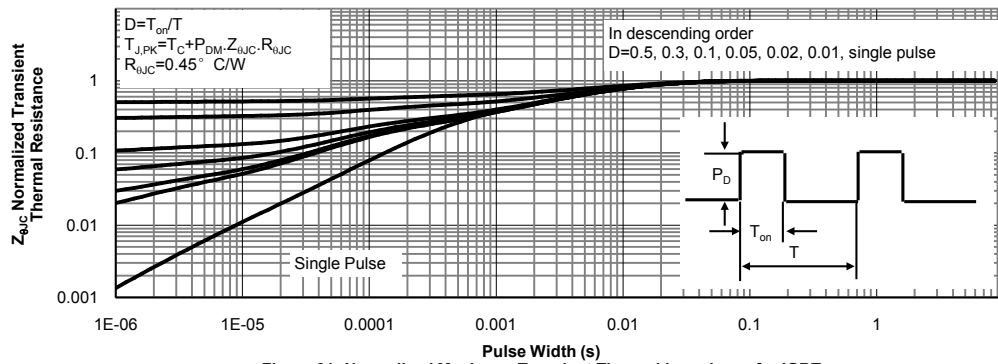
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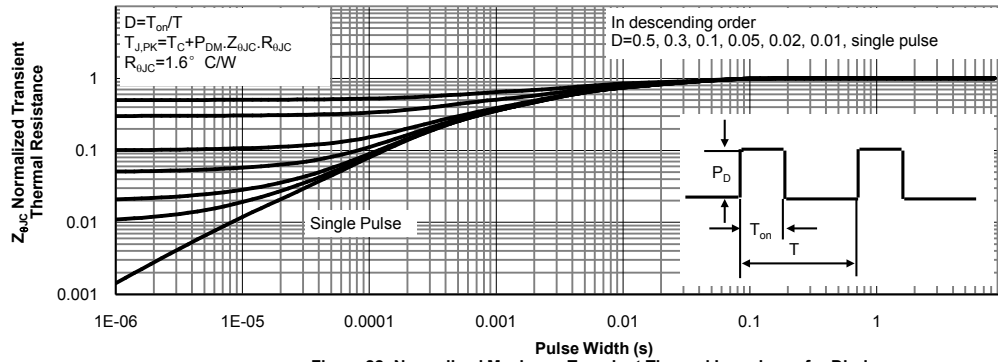
**Fig 19: Diode Reverse Leakage Current vs. Junction Temperature**



**Fig 20: Diode Forward Voltage vs. Junction Temperature**

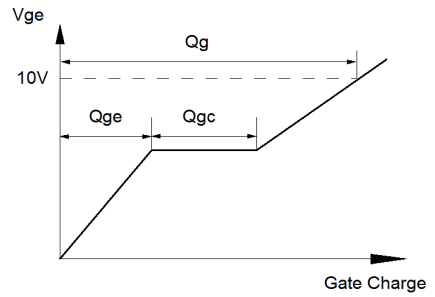
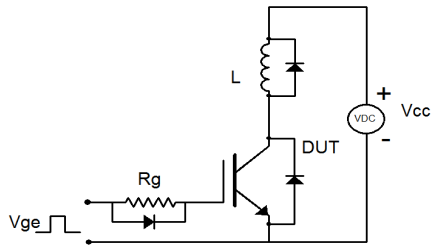


**Figure 21: Normalized Maximum Transient Thermal Impedance for IGBT**

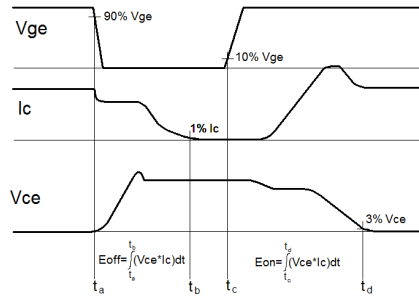
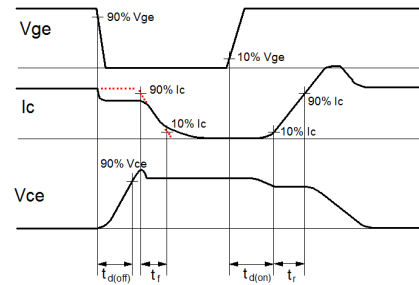
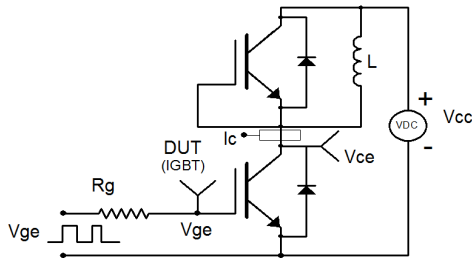


**Figure 22: Normalized Maximum Transient Thermal Impedance for Diode**

Gate Charge Test Circuit & Waveform



Inductive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

